

*SYSTEM FOR EFFICIENTLY CHANNELING HIGH FREQUENCY DATA SIGNALS
THROUGH SHEET METAL CONTAINMENT*

Abstract

5 A system is provided for channeling high frequency signals through sheet metal
containment within an electronic device. In exemplary embodiments of the invention, an
electronic device employing the system includes a midplane circuit board. One or more
interface modules may be coupled to the midplane circuit board, for example, for providing
a high frequency interconnect with other devices such as Fibre Channel or the like. A
10 midplane chassis shield is disposed within the device's housing adjacent to the midplane
circuit board so that the interface modules interconnect with the midplane circuit board
through apertures formed in the shield wherein the midplane circuit board, midplane chassis
shield and interface module cooperate for providing a low impedance tunnel for channeling
high frequency signals to ground.